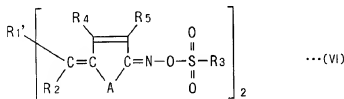
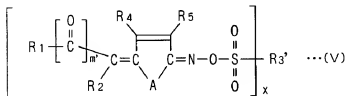


## AMENDMENTS TO THE CLAIMS

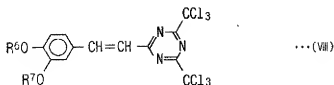
1. **(Previously presented)** A chemically amplified positive photosensitive thermosetting resin composition comprising:  
a reaction product of (A) an alkali soluble resin having a phenolic hydroxyl group and (C) a crosslinking polyvinyl ether compound;  
(B) a compound generating an acid under irradiation with radiation; and  
(D) an epoxy resin.

2. **(Currently amended)** A chemically amplified positive photosensitive thermosetting resin composition comprising (A) an alkali soluble resin, (B) a compound generating an acid under irradiation with radiation, (C) a crosslinking polyvinyl ether compound, and (D) an epoxy resin,

wherein (B) represented by the following general formulas (V), (VI), (VIII) or (X):



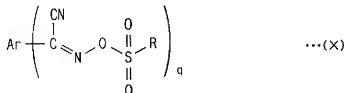
[wherein  $\text{m}'$  represents 0 or 1;  $\text{X}$  represents 1 or 2;  $\text{R}_1$  is a phenyl group which may be substituted with one or more  $\text{C}_1\text{-C}_{12}$  alkyl groups, or a heteroaryl group, or, when  $\text{m}'$  is 0,  $\text{R}_1$  may further be a  $\text{C}_2\text{-C}_6$  alkoxycarbonyl group, a phenoxycarbonyl group or  $\text{CN}$ ;  $\text{R}_1'$  represents a  $\text{C}_2\text{-C}_{12}$  alkylene group;  $\text{R}_2$  has the same meaning as in  $\text{R}_1$ ;  $\text{R}_3$  represents a  $\text{C}_1\text{-C}_{18}$  alkyl group;  $\text{R}_3'$  has the same meaning as in  $\text{R}_3$  when  $\text{X} = 1$ , or a  $\text{C}_2\text{-C}_{12}$  alkylene group or a phenylene group when  $\text{X} = 2$ ;  $\text{R}_4$  and  $\text{R}_5$  each independently represents a hydrogen atom, a halogen, or a  $\text{C}_1\text{-C}_6$  alkyl group;  $\text{A}$  represents  $\text{S}$ ,  $\text{O}$  or  $\text{NR}_6$ , and  $\text{R}_6$  represents a hydrogen atom or a phenyl group].



[wherein  $\text{R}^6$  and  $\text{R}^7$  each represents an alkyl group having 1 to 3 carbon atoms, or a combination of the compound (VIII) and a bis(trichloromethyl)triazine compound represented by the following formula (IX):



wherein Z represents a 4-alkoxyphenyl group,



[wherein Ar represents a substituted or unsubstituted phenyl group or a naphthyl group; R represents a  $\text{C}_1$  to  $\text{C}_9$  alkyl group; and q represents an integer of 2 or 3].

3. (Original) The chemically amplified positive photosensitive thermosetting resin composition according to claim 1, which comprises a curing accelerator for the component (D).

4. (Original) The chemically amplified positive photosensitive thermosetting resin composition according to claim 3, wherein the curing accelerator is a basic compound.

5. (Original) The chemically amplified positive photosensitive thermosetting resin composition according to claim 2, which comprises a curing accelerator for the component (D).

6. (Original) The chemically amplified positive photosensitive thermosetting resin composition according to claim 5, wherein the curing accelerator is a basic compound.

7. **(Original)** A method for formation of a cured article, which comprises applying the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6, subjecting to prebaking, subjecting to selective exposure, subjecting to PEB (post-exposure baking) and subjecting to alkali development to form a resist pattern, followed by melting with heating and further heat curing.

8. **(Original)** A cured article obtainable by the method of claim 7.

9. **(Original)** A method for production of a functional device, which comprises forming a resist pattern of and curing the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6.

10. **(Original)** A functional device obtainable by the method of claim 9.